

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**LISTING OF CLAIMS:**

Claim 1 (original): A nonreciprocal circuit device comprising:  
a center electrode assembly including a ferrite, a plurality of center electrodes and a plurality of insulating films defining a multilayer structure provided on a surface of the ferrite, and a plurality of side electrodes provided on side surfaces of the ferrite; wherein

each end portion of each of the plurality of center electrodes provided on the surface of the ferrite has a thickness greater than the thickness of the other portions of each of the plurality of center electrodes, and each thicker end portion of each of the plurality of center electrodes is connected to a corresponding side electrode.

Claim 2 (original): The nonreciprocal circuit device according to claim 1, wherein each thicker end portion of each of the plurality of center electrodes is made of a conductive material filled in a corresponding one of a plurality of openings provided in peripheral portions of the insulating films.

Claim 3 (original): The nonreciprocal circuit device according to claim 2, wherein the thickness of each end portion of the center electrode in a bottom layer of the multilayer structure on the surface of the ferrite is increased by a conductive material filled in a corresponding one of the plurality of openings formed in the insulating films on an upper surface of the end portion.

Claim 4 (original): The nonreciprocal circuit device according to claim 3, wherein the thickness of each end portion of the plurality of center electrodes in a top layer of the multilayer structure on the surface of the ferrite is increased by a conductive material filled in a corresponding one of the plurality of openings formed in the insulating films on a lower surface of the end portion.

Claim 5 (currently amended): The nonreciprocal circuit device according to claim 1, wherein the center electrodes are ~~made of a photosensitive conducting material~~ patterned using a photosensitive printing method.

Claim 6 (currently amended): The nonreciprocal circuit device according to claim 1, wherein the insulating films are ~~made of a photosensitive insulating material~~ patterned using a photosensitive printing method.

Claim 7 (original): The nonreciprocal circuit device according to claim 1, further comprising a metal case including a lower metal case and an upper metal case, said lower metal case having a bottom portion and right and left side portions, and said upper case having a top portion and four side portions.

Claim 8 (original): The nonreciprocal circuit device according to claim 1, wherein each of said thicker end portions has a thickness of about 40  $\mu\text{m}$ .

Claim 9 (original): The nonreciprocal circuit device according to claim 1, wherein said multilayer structure further comprises at least one shrinkage prevention sheet provided on at least one of an upper surface and a lower surface of the multilayer structure.

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Claim 10 (original): The nonreciprocal circuit device according to claim 1, wherein each of said plurality of center electrodes is made of a material selected from the group consisting of Ag, Cu and Ag-Pd.

Claim 11 (original): The nonreciprocal circuit device according to claim 1, wherein the ferrite is a microwave ferrite.

Claim 12 (original): A communication device including a nonreciprocal circuit device according to claim 1.

Claims 13-17 (canceled).